

REMARKS

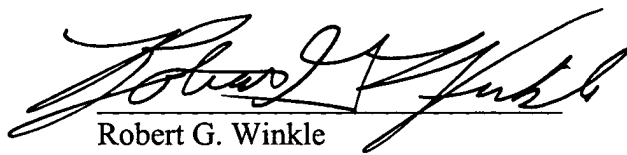
In response to the Restriction Requirement mailed on August 3, 2001, Applicants hereby elect Group II, claims 10-33, without transverse.

Claims 10-33 remain in the application. Independent claims 10, 21, and 23 have been amended to more clearly define the present invention. These amendments are supported in the specification at page 10, line 12 et seq. and FIGs. 5, 6a-c, 7, and 8.

An Information Disclosure Statement with a PTO-1449 is enclosed herewith. As no action on the merits has been received, no fee is believed due for the Information Disclosure Statement.

Please forward further communications to the address of record. If the Examiner needs to contact the below-signed attorney to further the prosecution of the application, the contact number is (503) 712-1682.

Respectfully submitted,



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VERSION OF CLAIMS WITH MARKINGS

IN THE CLAIMS:

1 10. (First Amended) A method of fabricating microelectronic dice, comprising:
2 providing a first encapsulated die assembly having an active surface and a back
3 surface, said first encapsulated die assembly including at least one first microelectronic
4 die having an active surface and at least one side and a first packaging material adjacent
5 said at least one first microelectronic die side, wherein said first packaging material
6 comprises a first microelectronic package core and a first encapsulation material, and
7 wherein said first encapsulation material comprises at least a portion of said first
8 encapsulation die assembly back surface; [and]
9 providing a second encapsulated die assembly having an active surface and a back
10 surface, said second encapsulated die assembly including at least one second
11 microelectronic die having an active surface and at least one side and a second packaging
12 material adjacent said at least one second microelectronic die side; and
13 attaching said first encapsulated die assembly back surface to said second
14 encapsulated assembly back surface.

1 21. (First Amended) The method of claim 10, wherein said providing a first
2 encapsulated die assembly comprises:
3 providing at least one first microelectronic die having an active surface
4 and at least one side;
5 abutting a protective film against said at least one first microelectronic die

6 active surface;
7 abutting said first microelectronic package core against said protective
8 film;
9 encapsulating said at least one microelectronic die with an encapsulation
10 material adjacent said at least one first microelectronic die side, wherein said
11 encapsulation material provides at least one surface of said encapsulation material
12 substantially planar to said first microelectronic die active surface; and
13 removing said protective film.

1 23. (First Amended) A method of fabricating a microelectronic package,
2 comprising:
3 forming a first encapsulated die assembly comprising:
4 providing at least one first microelectronic die having an active
5 surface and at least one side;
6 abutting a protective film against said at least one first
7 microelectronic die active surface;
8 abutting a first microelectronic package core against said protective
9 film; and
10 encapsulating said at least one microelectronic die with an
11 packaging material adjacent said at least one first microelectronic die side
12 to form a first encapsulated die active surface and a first encapsulated die
13 back surface;

14 forming a second encapsulated die assembly comprising:
15 providing at least one second microelectronic die having an active
16 surface and at least one side;
17 abutting a protective film against said at least one second
18 microelectronic die active surface; and
19 encapsulating said at least one microelectronic die with an
20 packaging material adjacent said at least one second microelectronic die
21 side to form a second encapsulated die active surface and a second
22 encapsulated die back surface; and
23 attaching said first encapsulated die assembly back surface to said second
24 encapsulated assembly back surface.